

DECLARATION AND POWER OF ATTORNEY

Atty. Dkt. No.: 2557-000220/US

DECLARATION

As a below named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

MOLDING METHOD AND MOLD FOR ENCAPSULATING BOTH SIDES OF PCB MODULE WITH WAFER LEVEL PACKAGE MOUNTED PCB

the specification of which (check one)

- is attached hereto.
- or
- was filed on _____ as Application Serial No. or PCT International Application No. _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim foreign priority benefits under 35 U.S.C. §§ 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or any PCT international application having a filing date before that of the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)				
APPN. SERIAL NO.	COUNTRY	DATE FILED (MM/DD/YYYY)	PRIORITY CLAIM	
			Yes	No
2003-9361	Korea	2/14/2003	<input checked="" type="checkbox"/>	<input type="checkbox"/>
2003-31152	Korea	5/16/2003	<input checked="" type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>

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I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below:

PRIOR PROVISIONAL APPLICATION(S)	
APPN. SERIAL NO.	DATE FILED (MM/DD/YYYY)

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s) listed below:

PRIOR U.S. APPLICATION(S)		
APPN. SERIAL NO.	DATE FILED (MM/DD/YYYY)	STATUS - PATENTED, PENDING, ABANDONED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY

I hereby appoint the following attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Thomas S. Auchterlonie	Reg. No. 37,275
John A. Castellano	Reg. No. 35,094
Terry L. Clark	Reg. No. 32,644
Donald J. Daley	Reg. No. 34,313
Gary D. Yacura	Reg. No. 35,416
Gregory P. Brummett	Reg. No. 41,646
Matthew Lattig	Reg. No. 45,274

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CORRESPONDENCE ADDRESS

I request the Patent and Trademark Office to direct all correspondence and telephone calls relative to this application to Harness, Dickey & Pierce, P.L.C., **Customer No. 30593**, P.O. Box 8910, Reston, Virginia, 20195, (703) 668-8000.

SANG-HYEOP LEE:

Inventor's signature: Sang-Hyeop Lee

Date: JAN. 1P. 2004

Residence: 101-706, Hyundai Apt., 219-4, Cheongsu-dong, Cheonan-si, Chungcheongnam-do, Republic of Korea

Citizenship: Republic of Korea

Mailing Address: 101-706, Hyundai Apt., 219-4, Cheongsu-dong, Cheonan-si, Chungcheongnam-do, Republic of Korea

HEE-KOOK CHOI:

Inventor's signature: Hee-Kook Choi

Date: JAN. 1P. 2004

Residence: 3-1001, Moran Apt., 653, Ssangyong-dong, Cheonan-si, Chungcheongnam-do, Republic of Korea

Citizenship: Republic of Korea

Mailing Address: 3-1001, Moran Apt., 653, Ssangyong-dong, Cheonan-si, Chungcheongnam-do, Republic of Korea

CHEOL-JOON YOO:

Inventor's signature: Cheol-Joon Yoo

Date: JAN 1P. 2004

Residence: 206-907, Cheongsol 2-cha Apt., Ssangyong 2-dong, Cheonan-si, Chungcheongnam-do, Republic of Korea

Citizenship: Republic of Korea

Mailing Address: 206-907, Cheongsol 2-cha Apt., Ssangyong 2-dong, Cheonan-si, Chungcheongnam-do, Republic of Korea